

# קורס דבקים. פרק ב. פריימרים והכנות שטח



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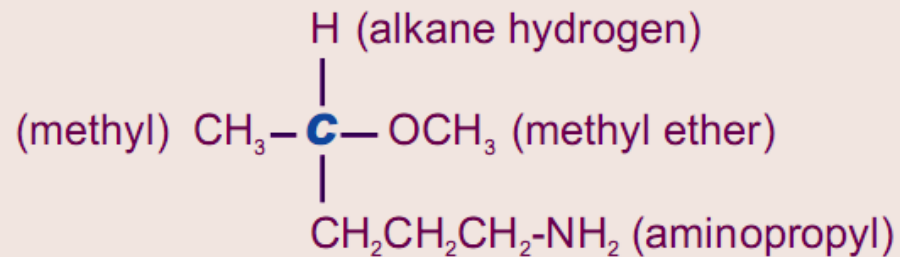
Home page: <http://atmp.co.il/index.php>

- פריימר הוא ציפוי דק, המיושם על מצע, לאחר שנוקה כהלכה, ומשפר את ההרטבה והחיבור של דבק למצע
- במקרים מיוחדים, הפריימר משמש לצורך הגנה על שטח הבין פנים מפני קורוזיה
- פריימר, מורכב בדרך כלל מ:
  - ממס
  - חומרים משפרי הרטבה (לא תמיד)
  - משפרי הדבקה (בדרך כלל סילאנים, אבל יכולים להיות גם טיטאנטים, זירקונאטים ופולימרים עם מספר חומצה גבוה)
  - פיגמנטים אנטי קורוזיביים (כאשר הפריימר מיועד להגנה על מתכות רגישות לקורוזיה)
  - פולימרים (לא תמיד)

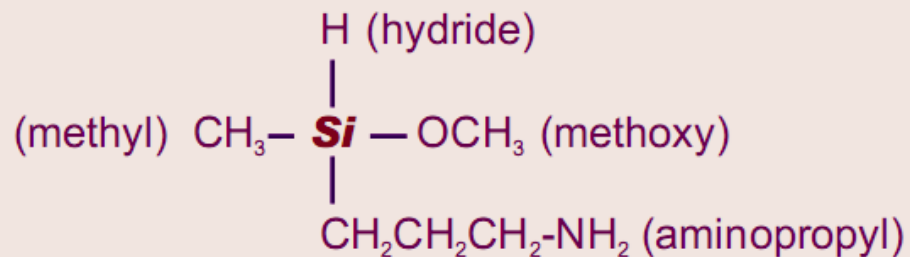
**פריימרים**

**Figure 1.** Carbon vs. silicon chemistry.

**Organic (Carbon-Based) Chemical**

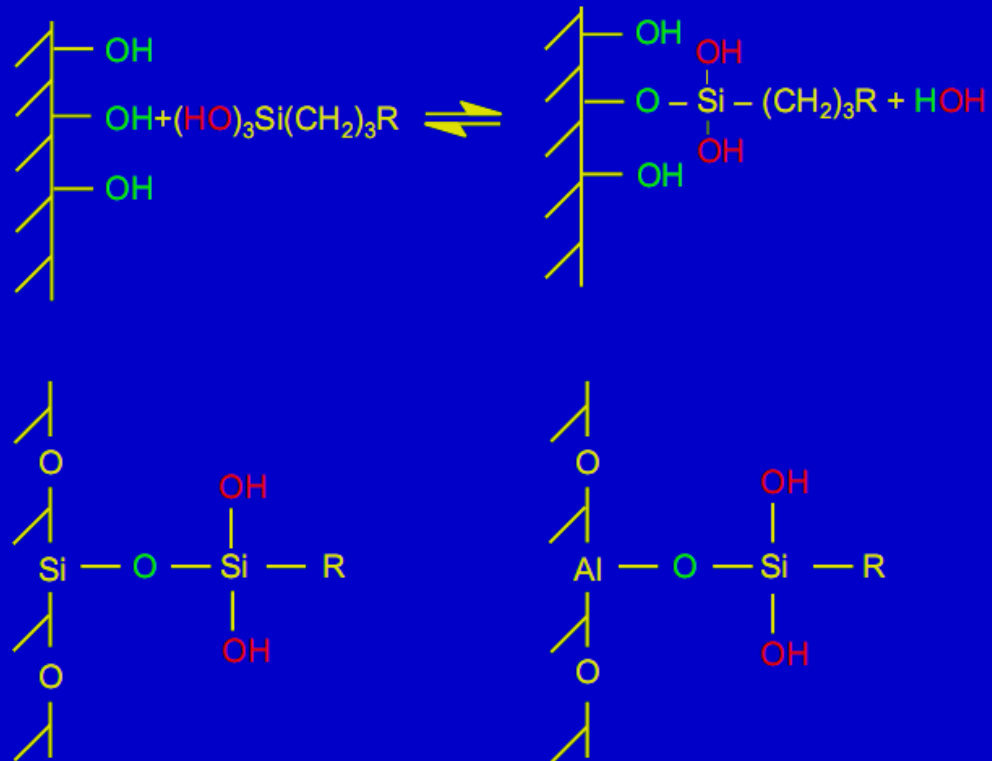


**Silane (Silicon-Based) Chemical**



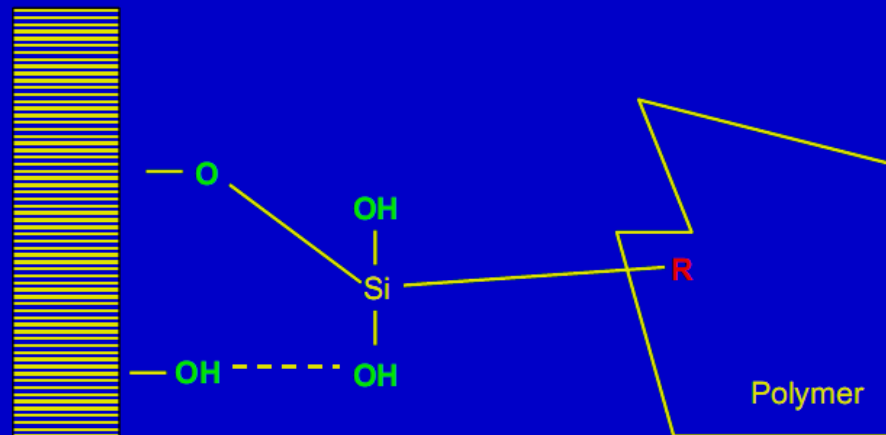
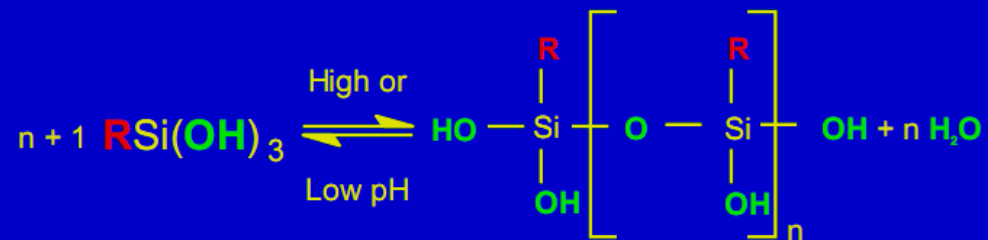
# סילאנים

Figure 6 Interaction of Active Surfaces with Silanols



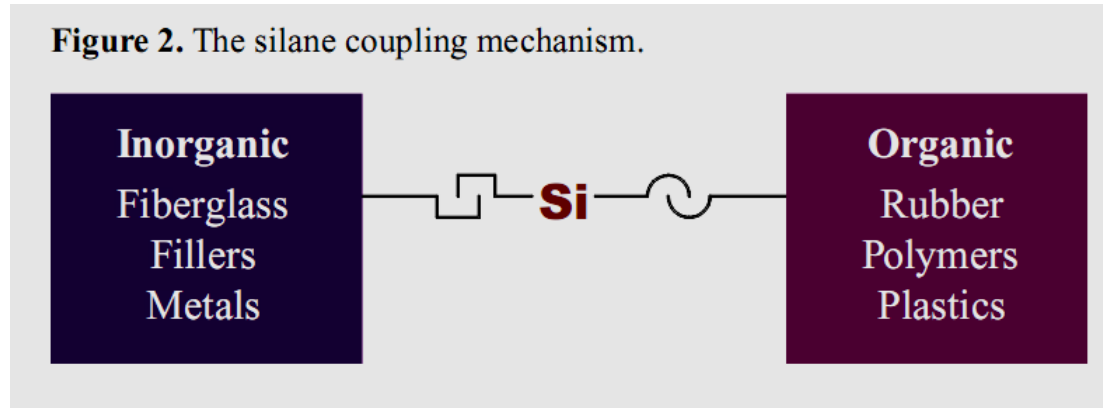
# סילאנים

Figure 8 Interaction of the Bound silane with a Polymer Matrix

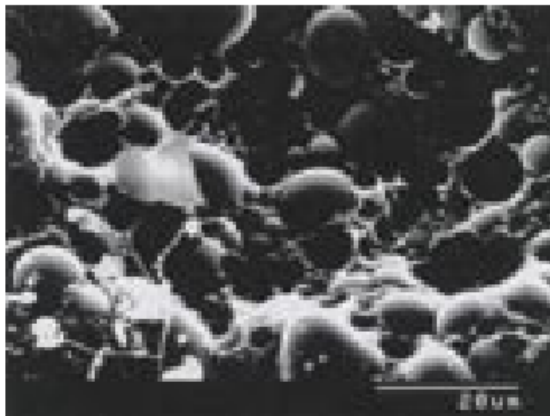


# סילאנים

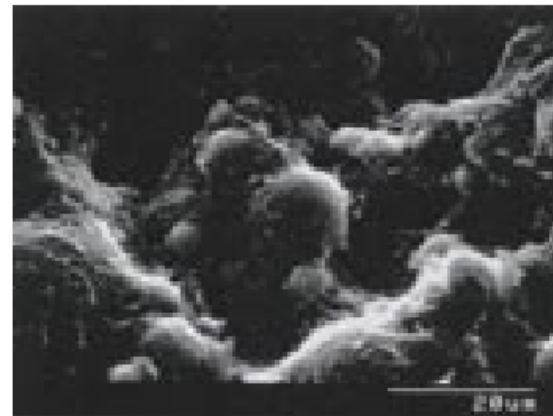
**Figure 2.** The silane coupling mechanism.



**Figure 3.** SEM of silica-filled epoxy resin.



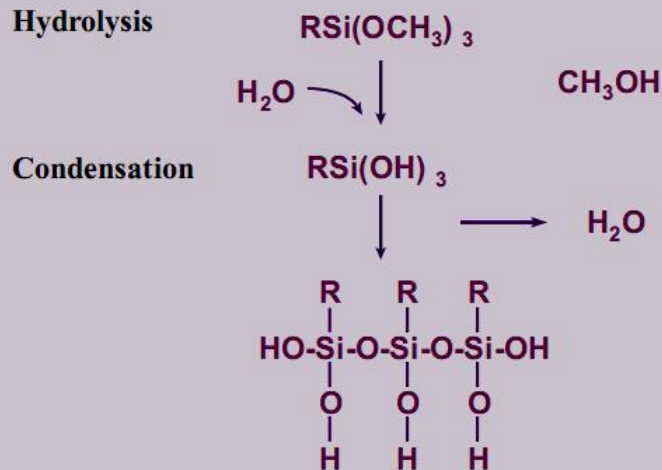
**Without Silane**



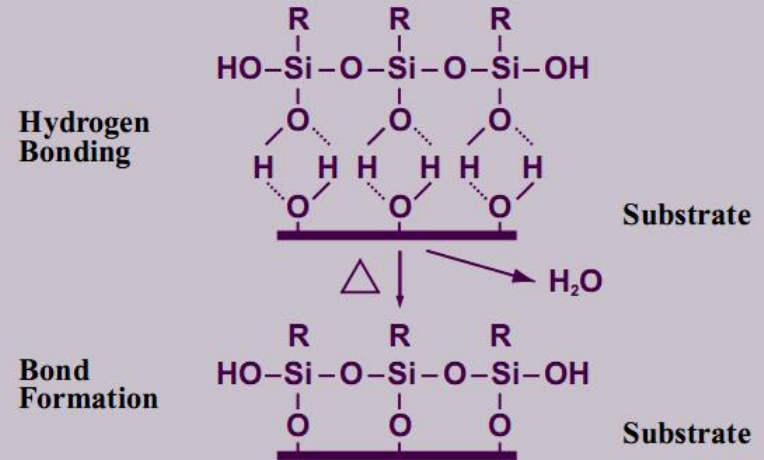
**With Silane**

# סילאנים

**Figure 4.** Hydrolysis of alkoxy silanes.

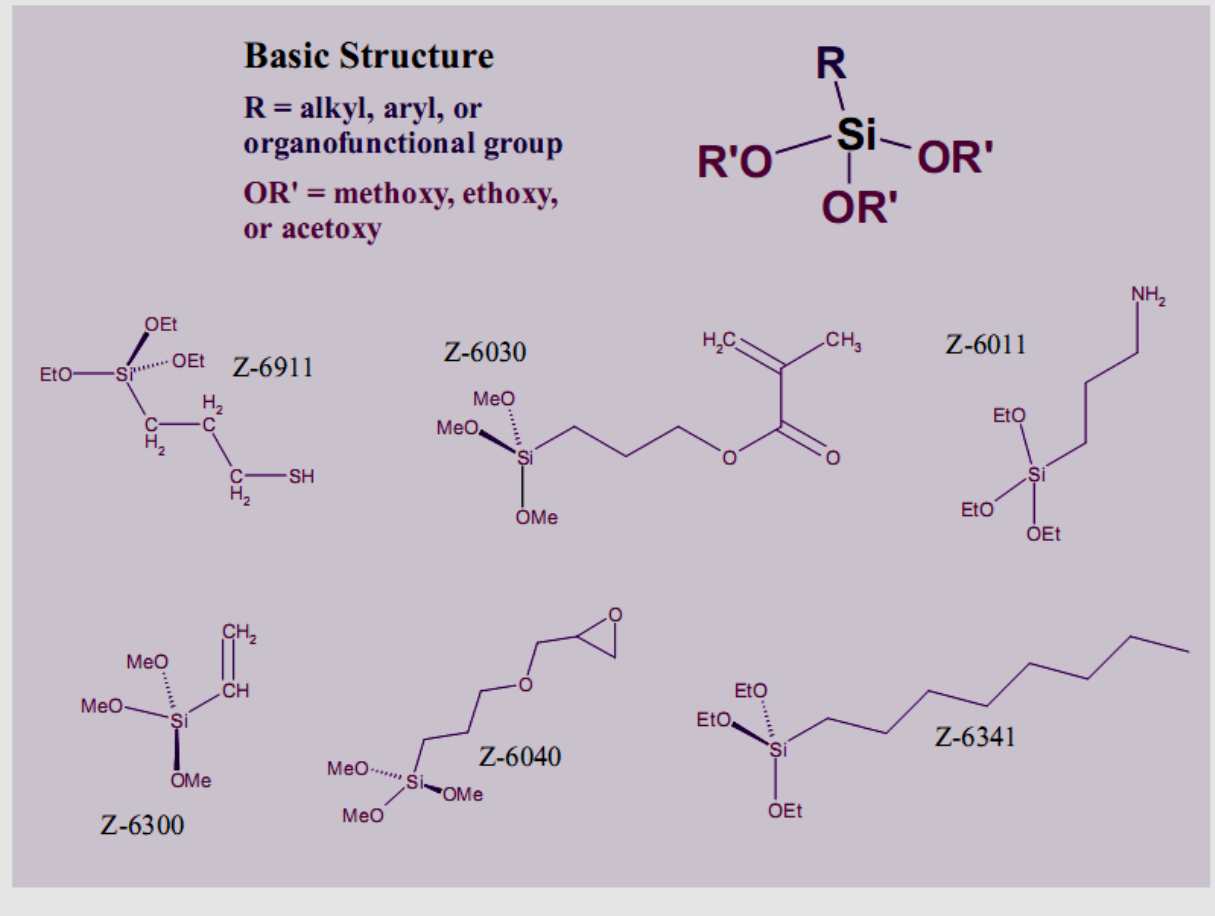


**Figure 5.** Bonding to an inorganic surface.



# סילאנים

Figure 7. Silane coupling agent variations – basic structure.





<b>Dow Corning® brand Silane</b>	<b>Organic Reactivity</b>	<b>Application (suitable polymers)</b>
Z-6011	Amino	Acrylic, Nylon, Epoxy, Phenolics, PVC, Urethanes, Melamines, Nitrile Rubber
Z-6020	Amino	Acrylic, Nylon, Epoxy, Phenolics, PVC, Melamines, Urethanes, Nitrile Rubber
Z-6028	Benzylamino	Epoxies for PCBs, Polyolefins, All Polymer Types
Z-6030	Methacrylate	Unsaturated Polyesters, Acrylics, EVA, Polyolefin
Z-6032	Vinyl-benzyl-amino	Epoxies for PCBs, Polyolefins, All Polymer Types
Z-6040	Epoxy	Epoxy, PBT, Urethanes, Acrylics, Polysulfides
Z-6076	Chloropropyl	Urethanes, Epoxy, Nylon, Phenolics, Polyolefins
Z-6094	Amino	Acrylic, Nylon, Epoxy, Phenolics, PVC, Melamines, Urethanes, Nitrile Rubber
Z-6106	Epoxy/Melamine	Epoxy, Urethane, Phenolic, PEEK, Polyester
Z-6128	Benzylamino	Epoxies for PCBs, Polyolefins, All Polymer Types
Z-6137	Amino	Acrylic, Nylon, Epoxy, Phenolics, PVC, Melamines, Urethanes, Nitrile Rubber (especially suited for water-based systems)
Z-6224	Vinyl-benzyl-amino	Epoxies for PCBs, Polyolefins, All Polymer Types
Z-6300	Vinyl	Graft to Polyethylene for Moisture Crosslinking, EPDM Rubber, SBR, Polyolefin
Z-6376	Chloropropyl	Urethanes, Epoxy, Nylon, Phenolics, Polyolefins
Z-6518	Vinyl	Graft to Polyethylene for Moisture Crosslinking, EPDM Rubber, SBR, Polyolefin
Z-6675	Ureido	Asphaltic Binders, Nylon, Phenolics; Urethane
Z-6910	Mercapto	Organic Rubber
Z-6920	Disulfido	Organic Rubber
Z-6940	Tetrasulfido	Organic Rubber

# סילאנים עם קבוצות פעילות שונות

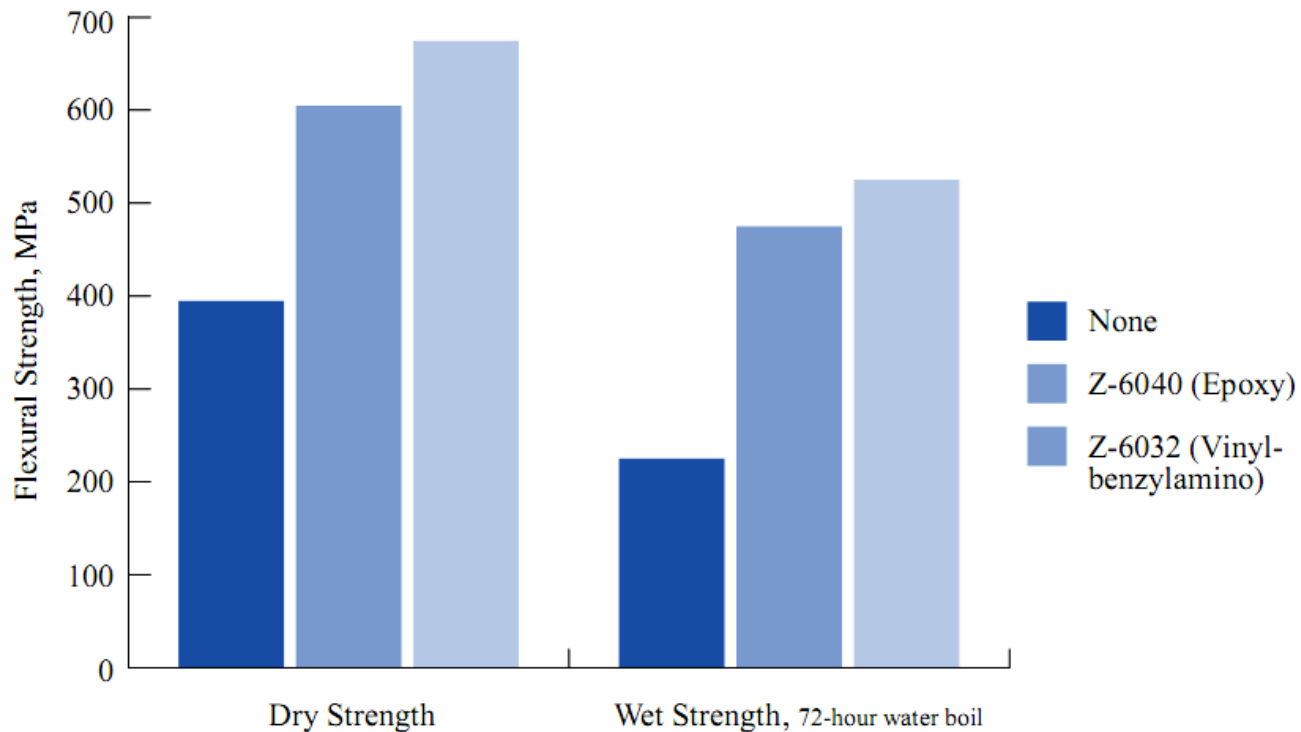
# סילאנים

**Table 4: Selection of silane adhesion promoters**

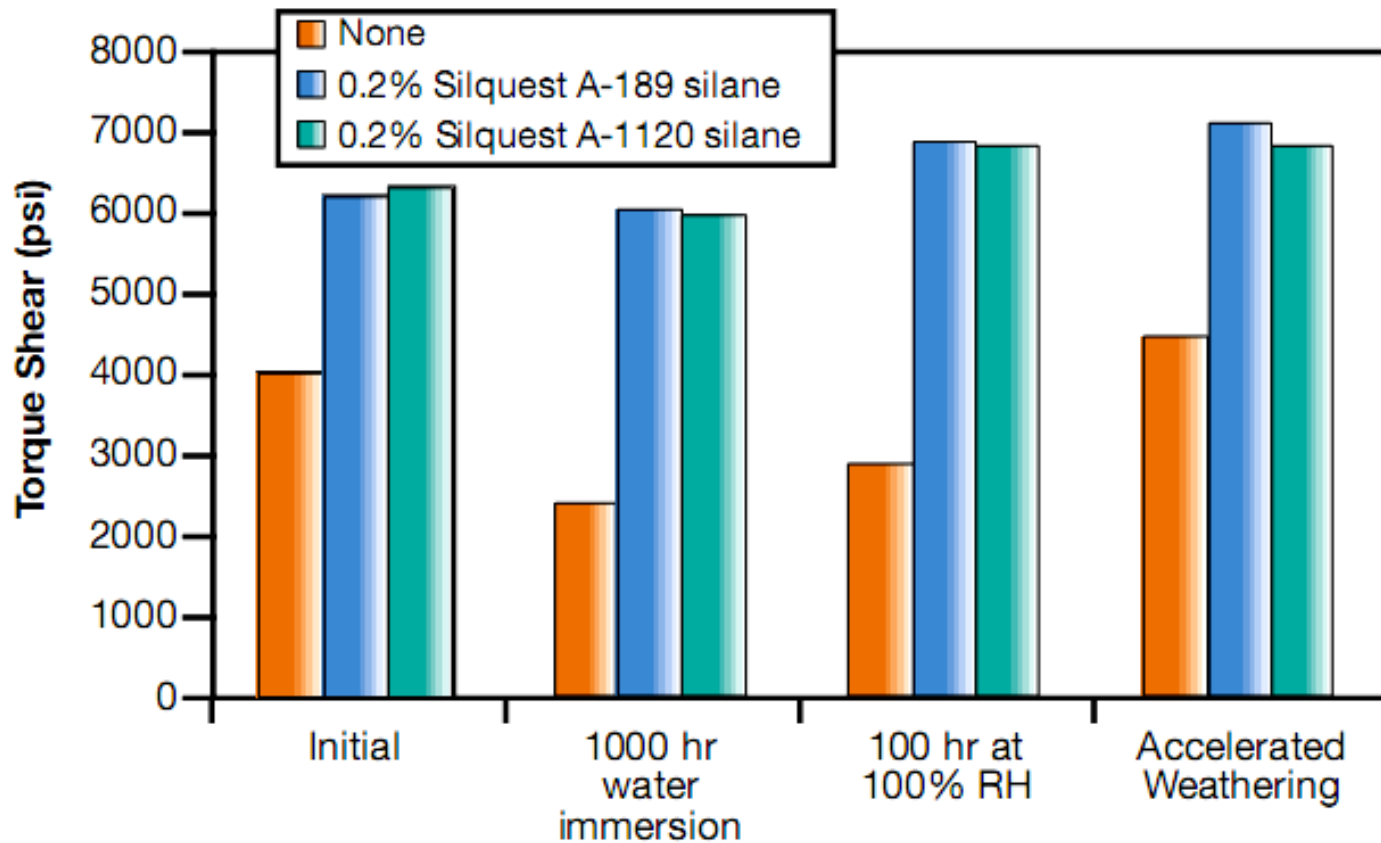
Organofunctional group of the silane adhesion promoter	Recommended for the following polymers
Amino	Epoxy, phenol, melamine, furan, urea, PVC, urethane, polyvinylbutyral, polyimide, polychloroprene, nitrile rubber, etc.
Vinyl, methacryl	Unsaturated polyesters, EPDM, polyolefins, urethane, alkyd
Epoxy	Epoxy, phenol, epichlorohydrin, PVC, polyester, urethane, polysulphide
Mercapto	All elastomers, urethane, polysulphide, PVC
Urea	Phenol, urea or melamine resins, epoxy resins
Chloro	Epoxy resins, polyurethane, thermoplastics

# סילאנים

**Figure 9.** Effect of silane coupling agents on the strength of glass-reinforced epoxy.



**Figure 4: Improved Wet and Dry Adhesion of Epoxy Paint to Aluminum**



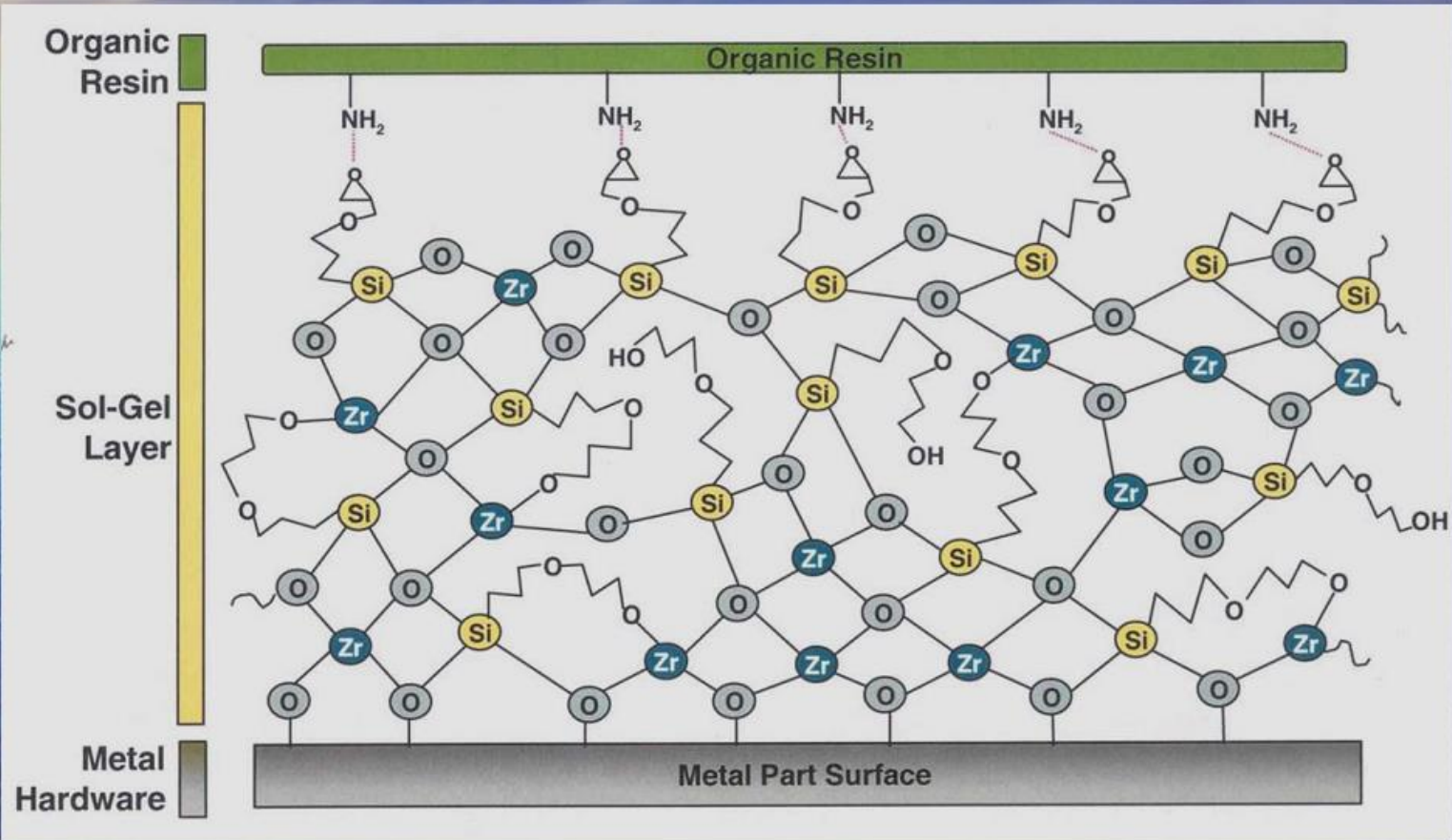
# הרכב טיפוסית של פריימר

**Table 1: Typical Silane Primer Recipe**

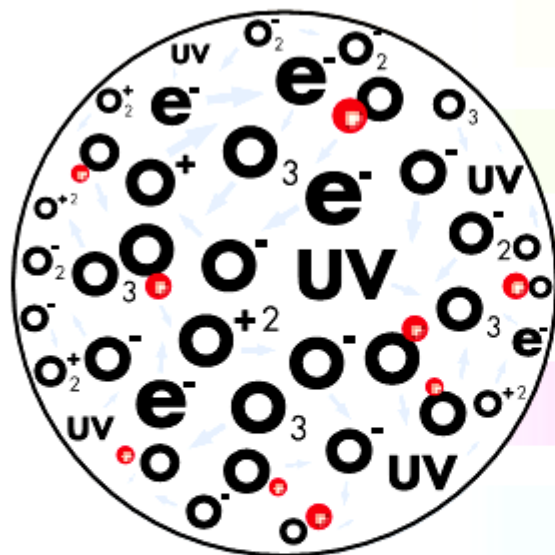
Parts by Weight	Ingredient
5	Organofunctional silane
40	SDA - alcohol
5	Distilled water
40	Xylene
5	n-butanol
4	2-butoxyethanol

Product formulations are included as illustrative examples only. Momentive makes no representation or warranty of any kind with respect to any such formulations, including, without limitation, concerning the efficacy or safety of any product manufactured using such formulations.


# Sol- Gel Interphase



# פלסמה



PLASMA

 Free Radical (highly reactive)

$O_3$  Ozone

$O^- O_2^-$  Negative Ions

**UV** Ultraviolet Light Photon

$O^+ O_2^+ O_3^+$  Positive Ions

$e^-$  Electron

This illustration summarizes the active species that are present in an oxygen plasma.

# פלסמה

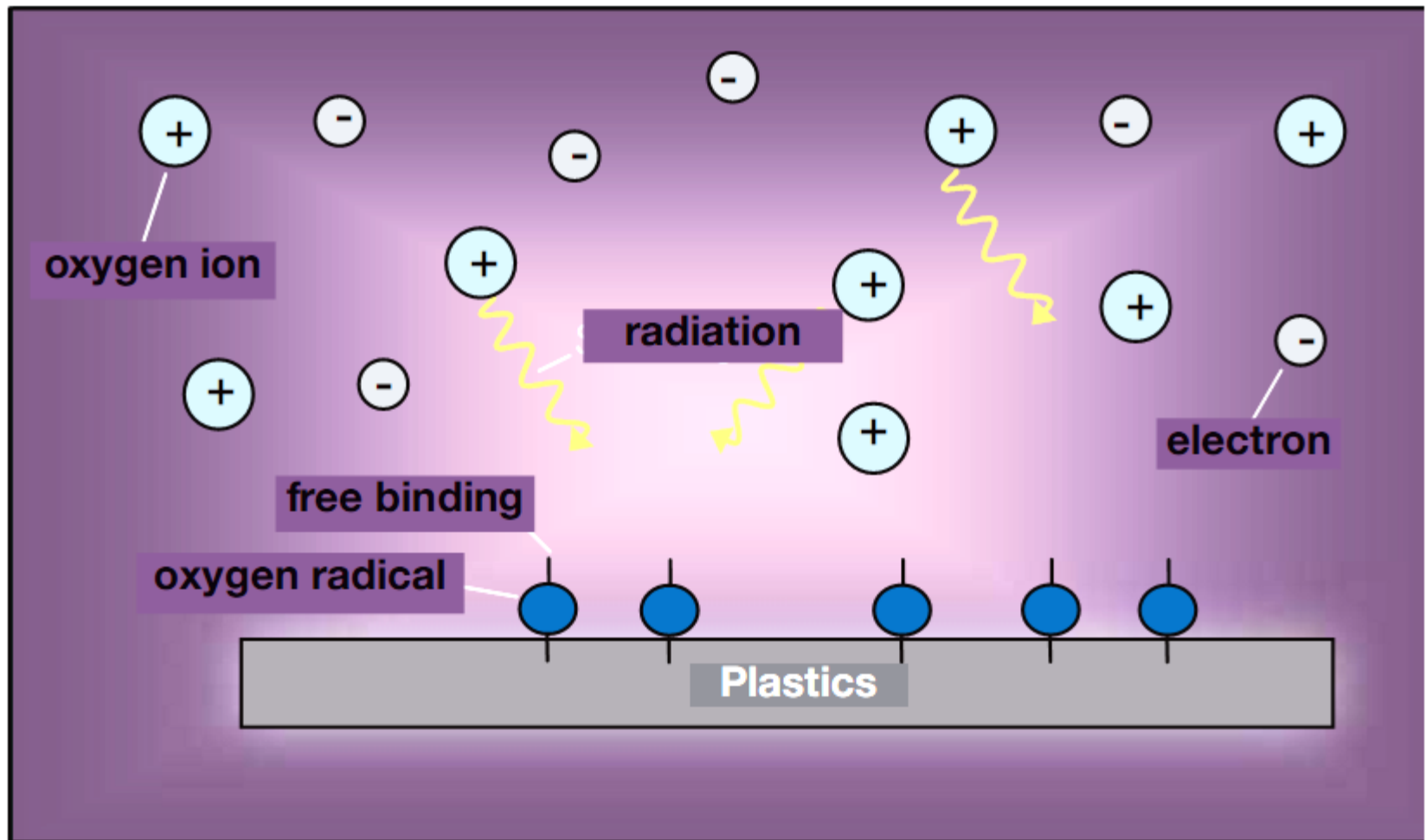


fig. 19: effects on plasma process



# פלסמה



Figure 2 The electrically neutral Openair plasma beam allows microscopically fine cleaning, high activation and paper-thin coating of surfaces

Photo:  
Plasmatreat



Treatment Chamber Window.



Plasma Treatment in Action.

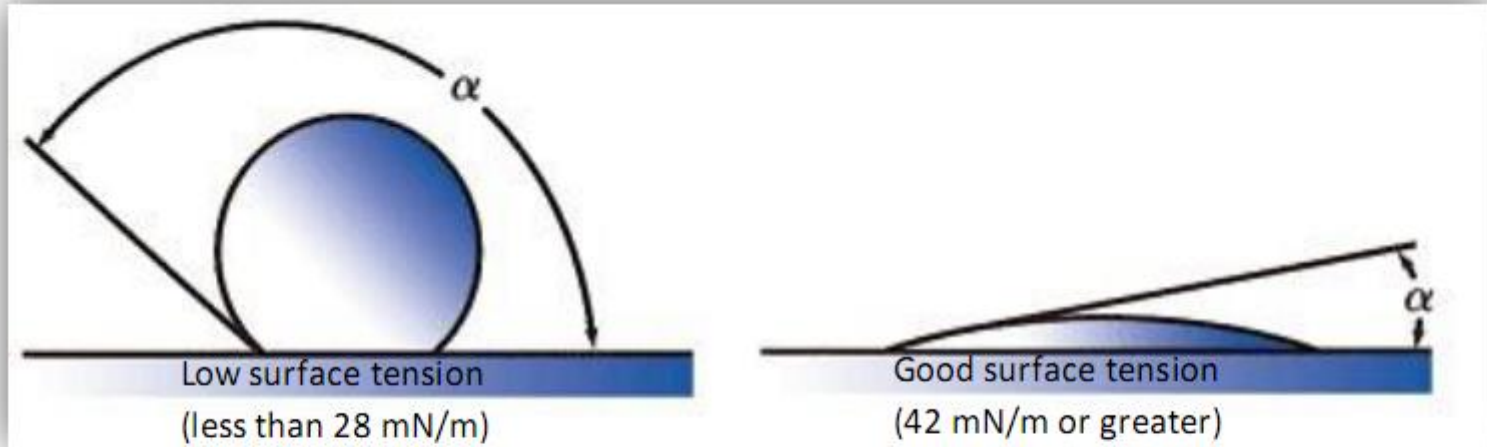


Figure 4 - Surface Tension for Adhesion (5)

Medical	Electronics	Packaging	Industrial	Optics
				
Syringes Catheters Tubing	Cell Phones Appliances PDAs	Lids/Caps Bottles Cups	Tubes Pipes Moldings	Lenses Fiber Optics Mirrors

Figure 8 - Air Plasma Treatment Applications (13)

# Plasma assisted surface modification

## Advantages

- Environmental friendly
- Allows to deposit coatings with unique properties
- Flexible switching between process conditions
- Reliable operation
- Energy efficient

# Why Atmospheric plasma technology ?

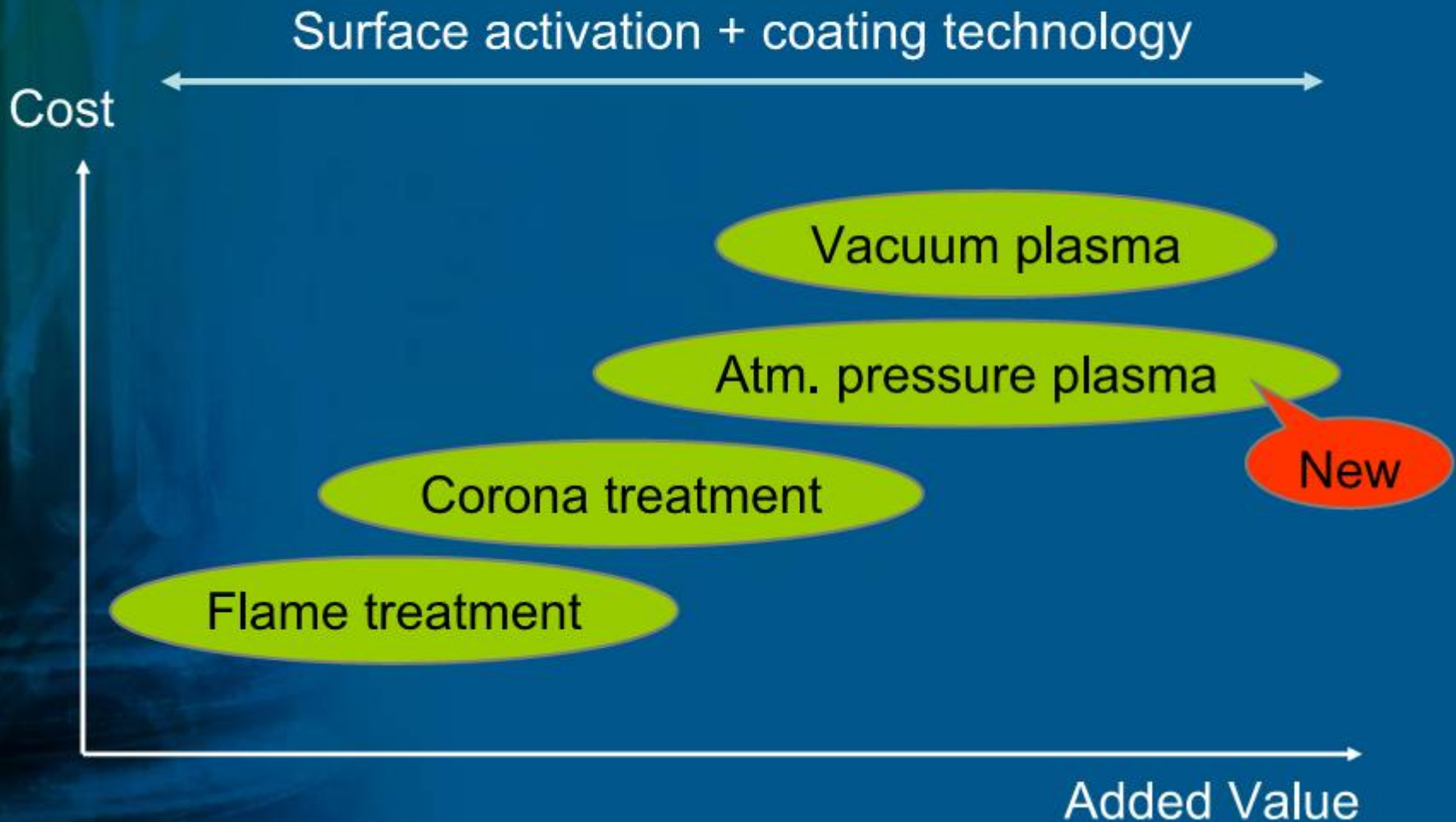




fig. 16: helium plasma



fig. 17: oxygen plasma, high pressure



fig. 18 : oxygen plasma, low pressure

# פלסמה

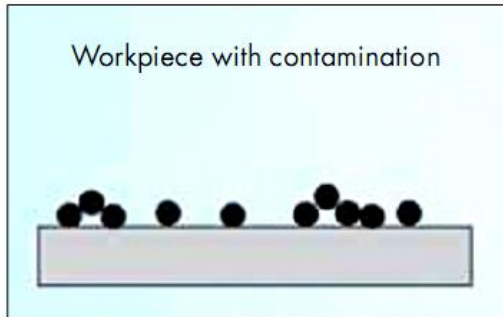


fig. 20: Before plasma treatment

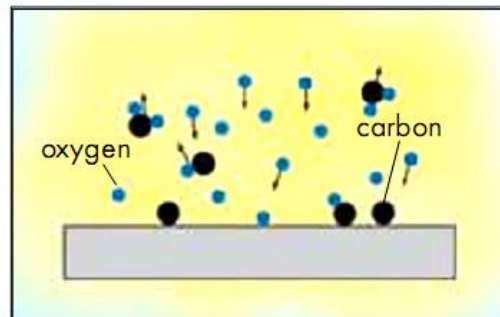


fig. 21: plasma treatment



fig. 22: After plasma treatment

# פלסמה



fig. 45: Before plasma treatment

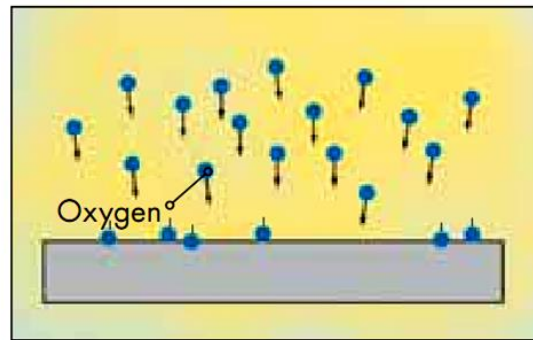


fig. 46: plasma treatment

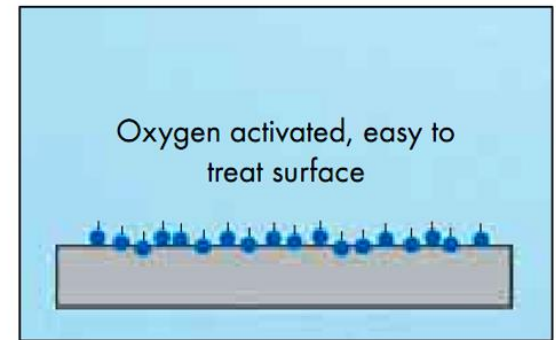


fig. 47: After plasma treatment



# פלסמה

Low-pressure plasma also enables coating of components (fig. 51-53).

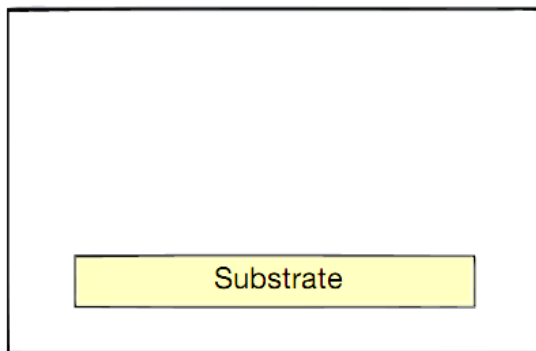


fig. 51: before plasma treatment

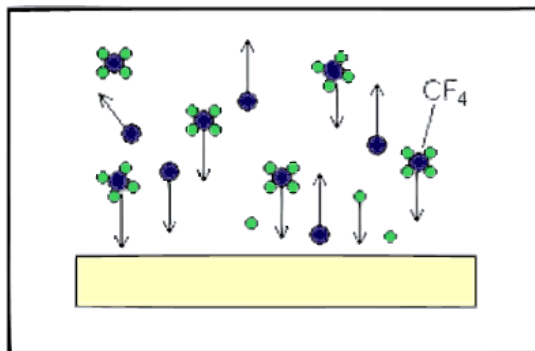


fig. 52: plasma treatment

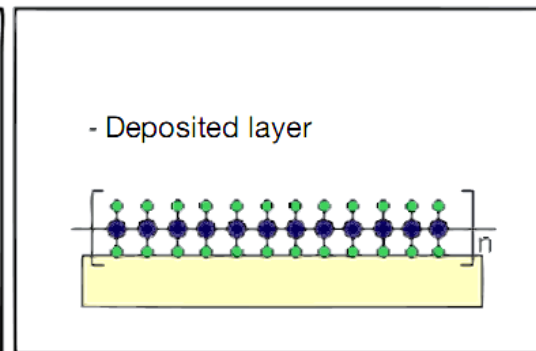
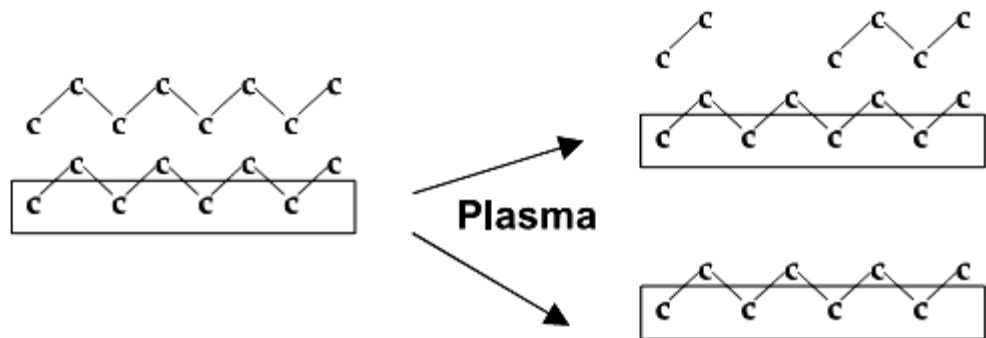


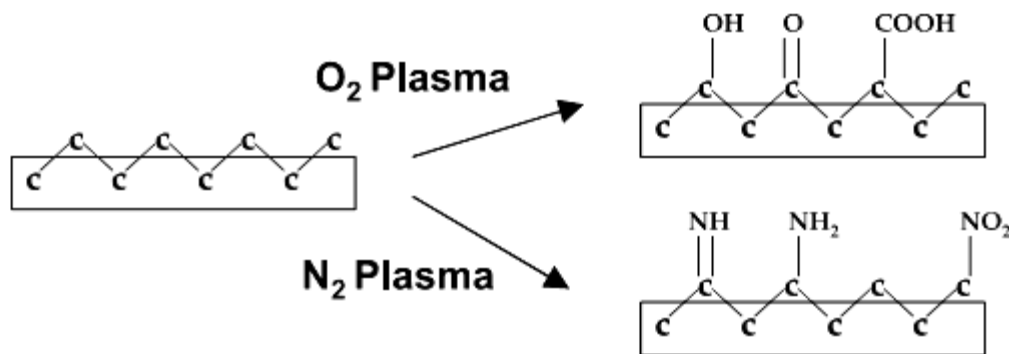
fig. 53: after plasma treatment

# Plasma assisted surface modification

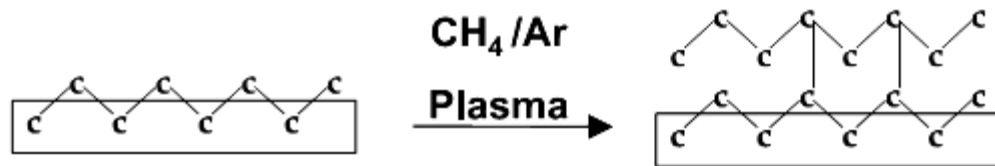
Cleaning, etching  
and sterilisation



Activation



Coating



# פלסמה

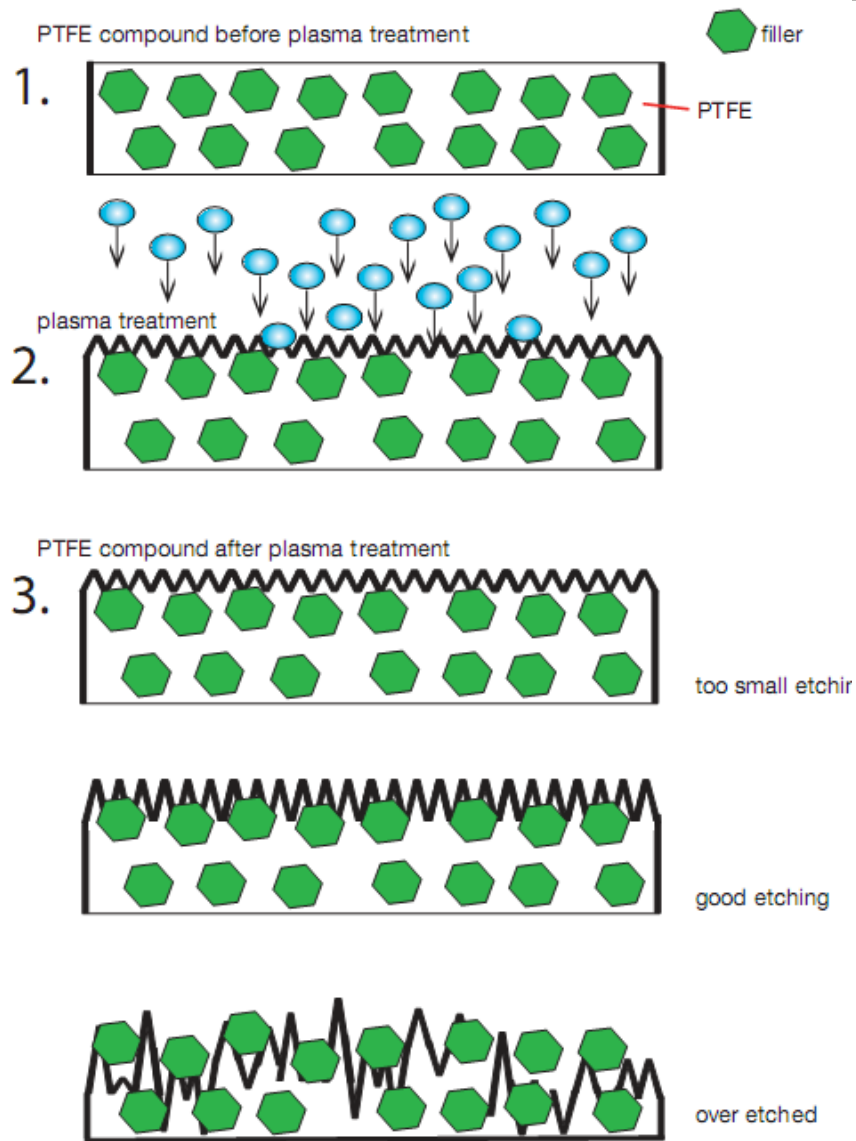


fig. 71: plasma etching of PTFE compounds

# פלסמה

## B. Reduction of Oxides:

- Metal oxide **chemically** reacts with the process gas (fig. 23-25). Pure hydrogen or a mixture of argon and nitrogen is used as a process gas.

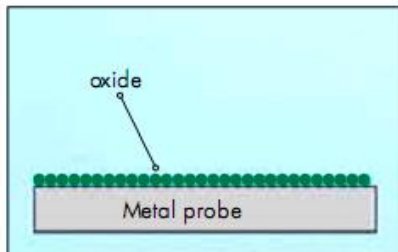


fig. 23: Before plasma treatment

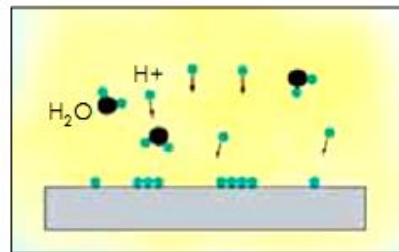


fig. 24: plasma treatment

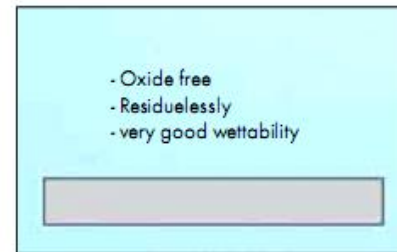


fig. 25: After plasma treatment

It is also possible to execute processes in **two stages**. For example treated parts are first oxidised with oxygen for 5 min (fig. 20-22) then they get reduced by argon-hydrogen (e.g. mixture of 90% argon and 10% hydrogen) (fig. 23-25).



fig. 26, 27, 28 : Examples for cleaning application of metals

# פלסמה

Examples of a variety of applications of plasma activation and plastic surface areas:



fig. 29: contact lens



fig. 30: catheter



fig. 31: telephone receiver



fig. 32: prosthesis

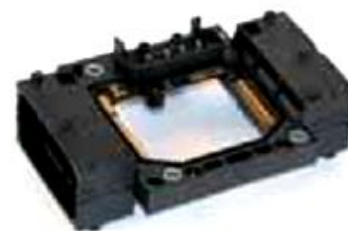


fig. 33: automotive components

# פלסמה

Example of photos (taken under the microscope)



fig. 37: untreated surface



fig. 38: activated surface



fig. 39: untreated surface

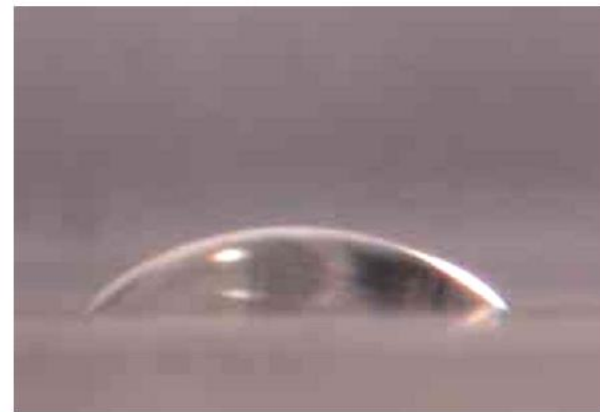


fig. 40: activated surface

# פלסמה

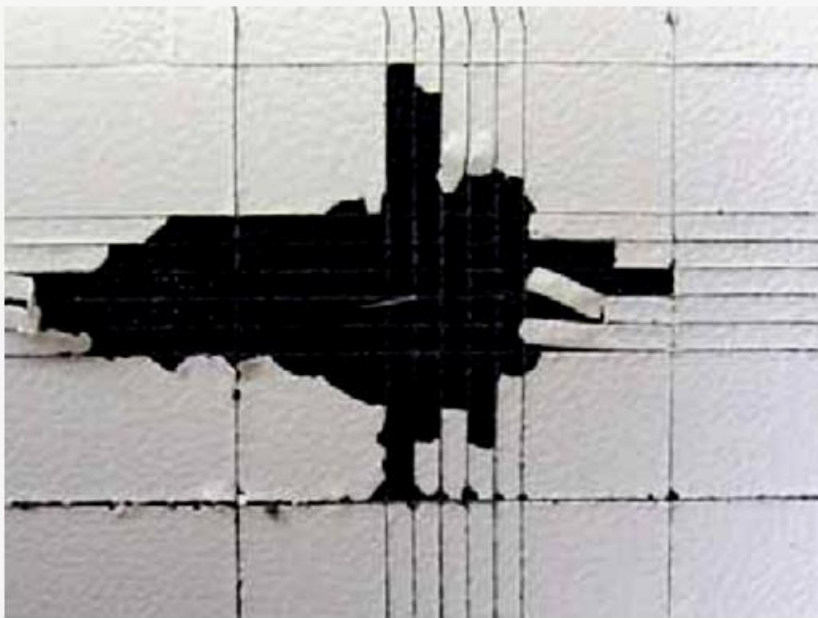


fig. 43: Grid-cut test, untreated

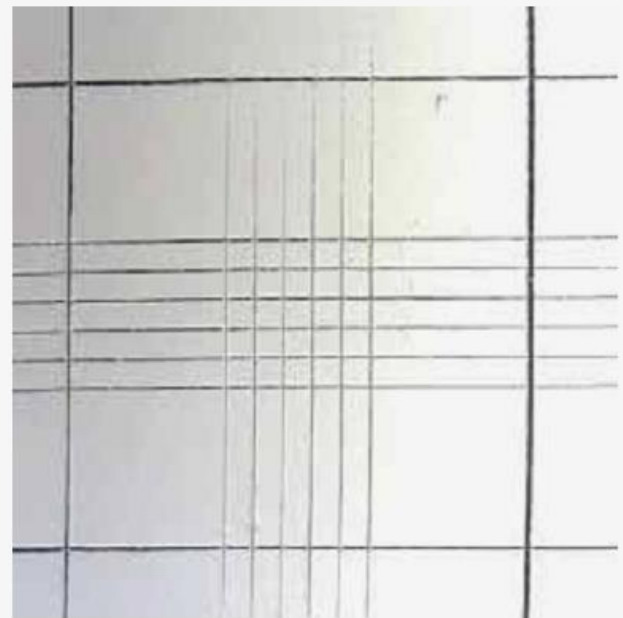


fig. 44: grid-cut test, treated

# פלסמה

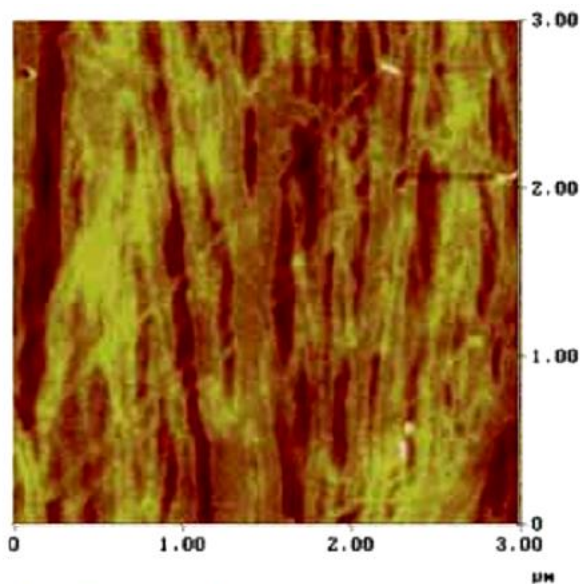


fig. 51: AFM picture of a untreated PC surface

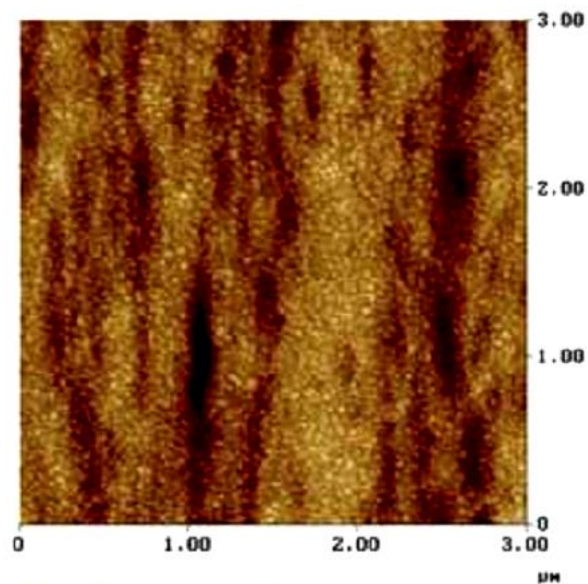


fig. 52: AFM picture of a O<sub>2</sub>-plasma treated PC surface

Pictures with kindly permission of Dr. Ina. Andreas Heegenbarth, IKV Aachen

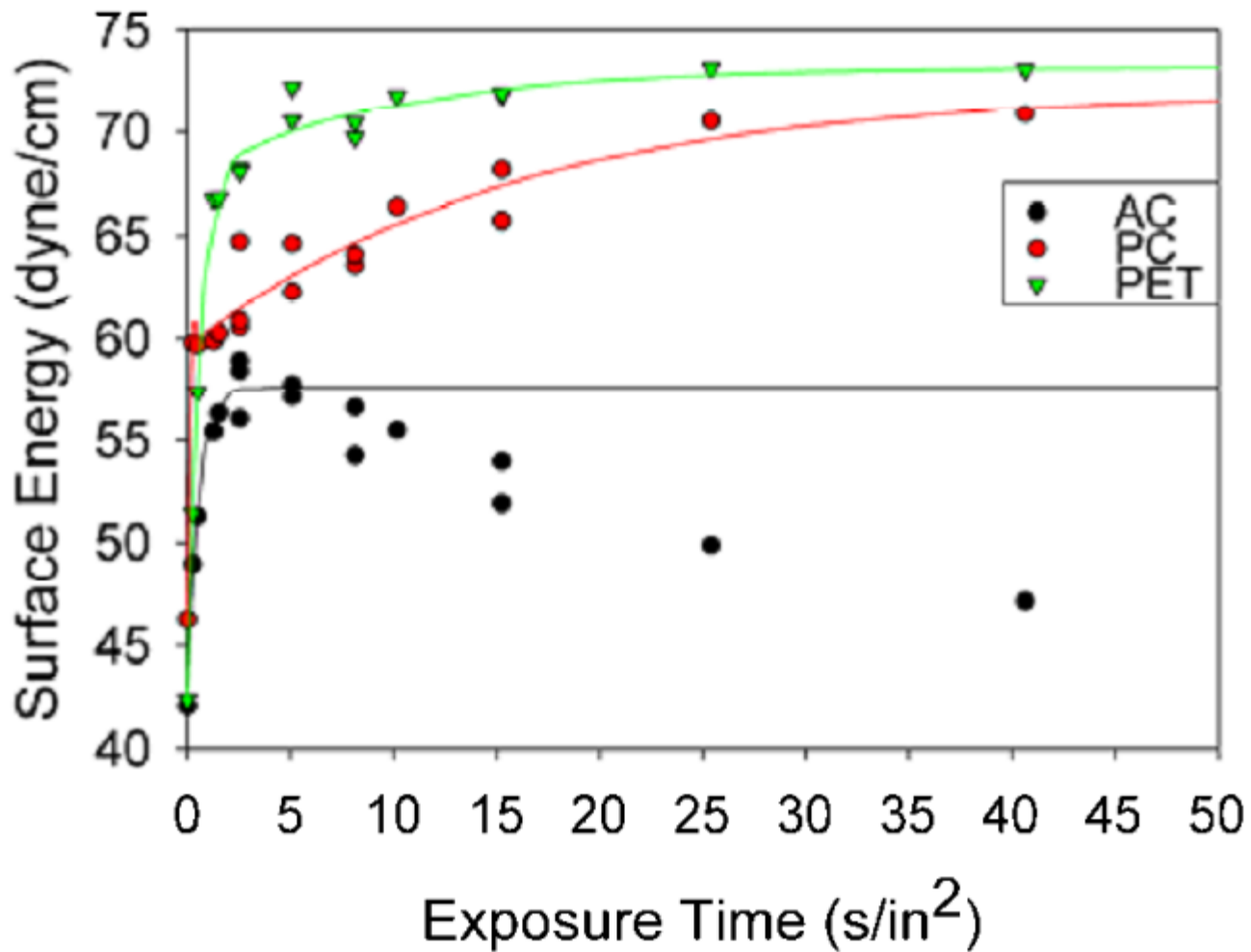


## Process Applications for Plasma Surface Enhancements

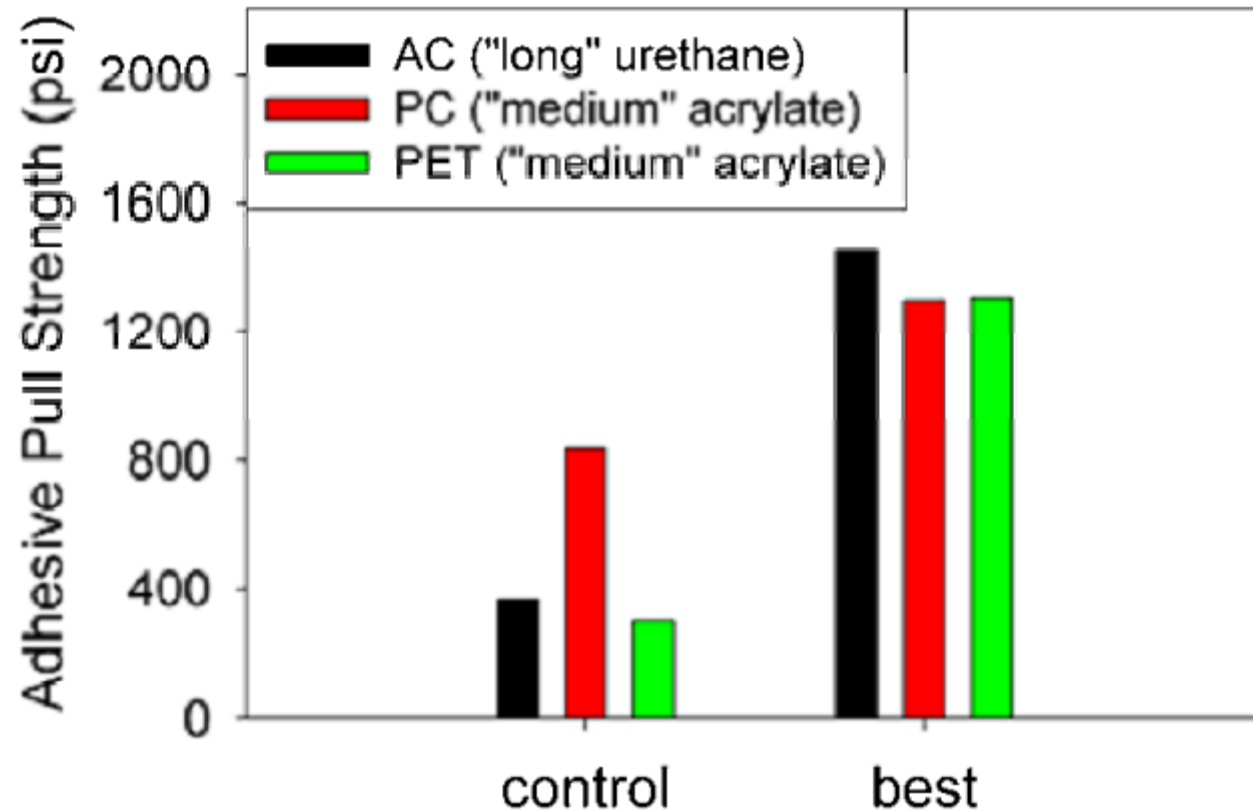
Plasma Source Gas	Surface Modification Processes	Advanced Technology Application
Argon (Ar)	Contamination Removal–Ablation	Wirebond Die Attach
	Cross Linking	Substrate Polymer–Metal Adhesion
Oxygen (O <sub>2</sub> )	Contamination Removal–Chemical Oxidation Process (Organic Removal)	Wirebond Die Attach
	Surface Activation	Mold and Encapsulant Adhesion
	Etch	Photoresist Removal
Nitrogen (N <sub>2</sub> )	Surface Activation	Mold and Encapsulant Adhesion
Hydrogen (H <sub>2</sub> )	Contamination Removal–Chemical Reduction Process (Metal Oxide Removal)	Wirebond Eutectic Die Attach
Carbon Tetrafluoride (CF <sub>4</sub> ) and Oxygen (O <sub>2</sub> ) or Sulfur Hexafluoride (SF <sub>6</sub> ) and Oxygen (O <sub>2</sub> )	Etch	Polymer Etch–Fiber Stripping Photoresist Removal
		Thin Film Etch–Oxides, Nitrides

<b>Hydrocarbons</b>	<b>Before</b>	<b>After</b>
<b>Polypropylene</b>	87°	22°
<b>Polyethylene</b>	87°	22°
<b>Polyamide (nylon)</b>	73°	15°
<b>Polyimide</b>	79°	10°
<b>Polycarbonate</b>	75°	33°

Table 1 - Typical Wetting Angles Before and After Oxygen Plasma Surface Treatment (4)



**Figure 2. The effect of the oxygen-helium plasma on the surface energy of the polymers.**



**Figure 4. Adhesion pull test data for AC, PC and PET with the best combination of adhesive and plasma treatment.**



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